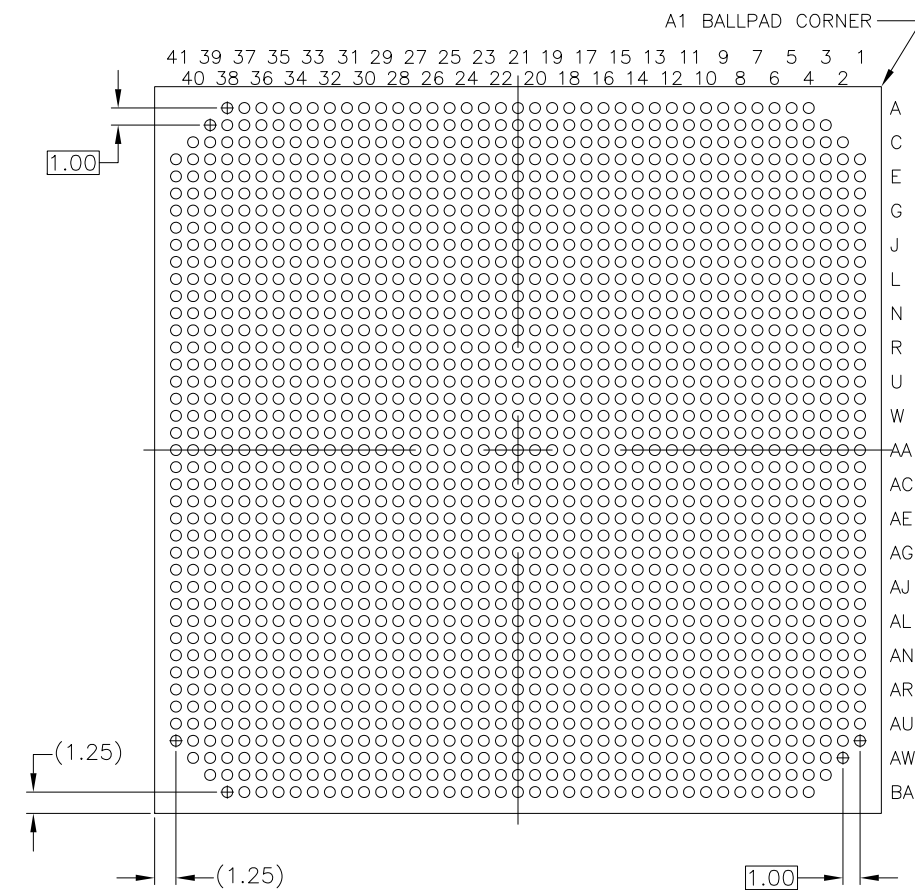
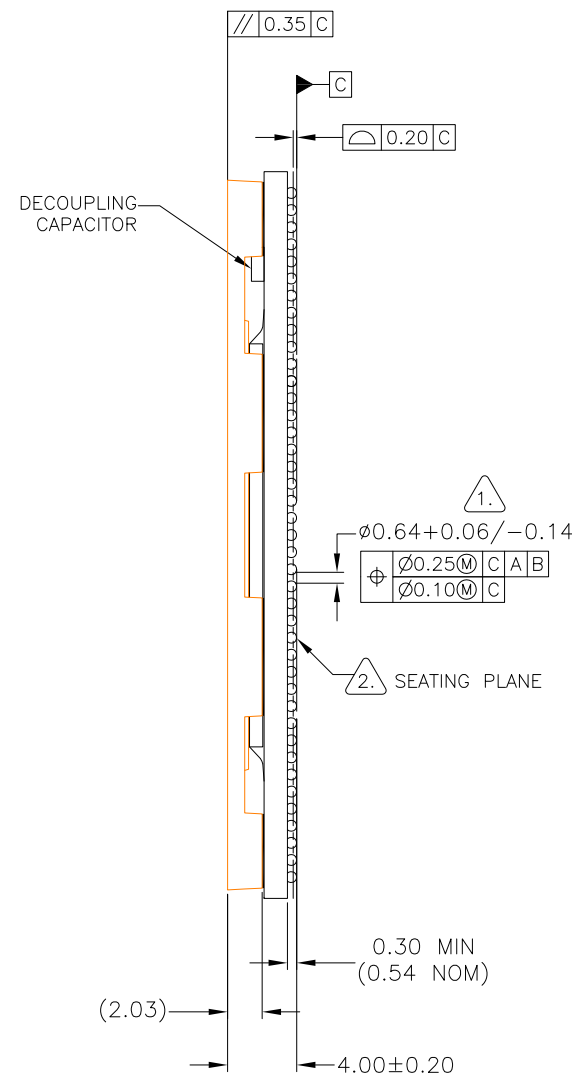
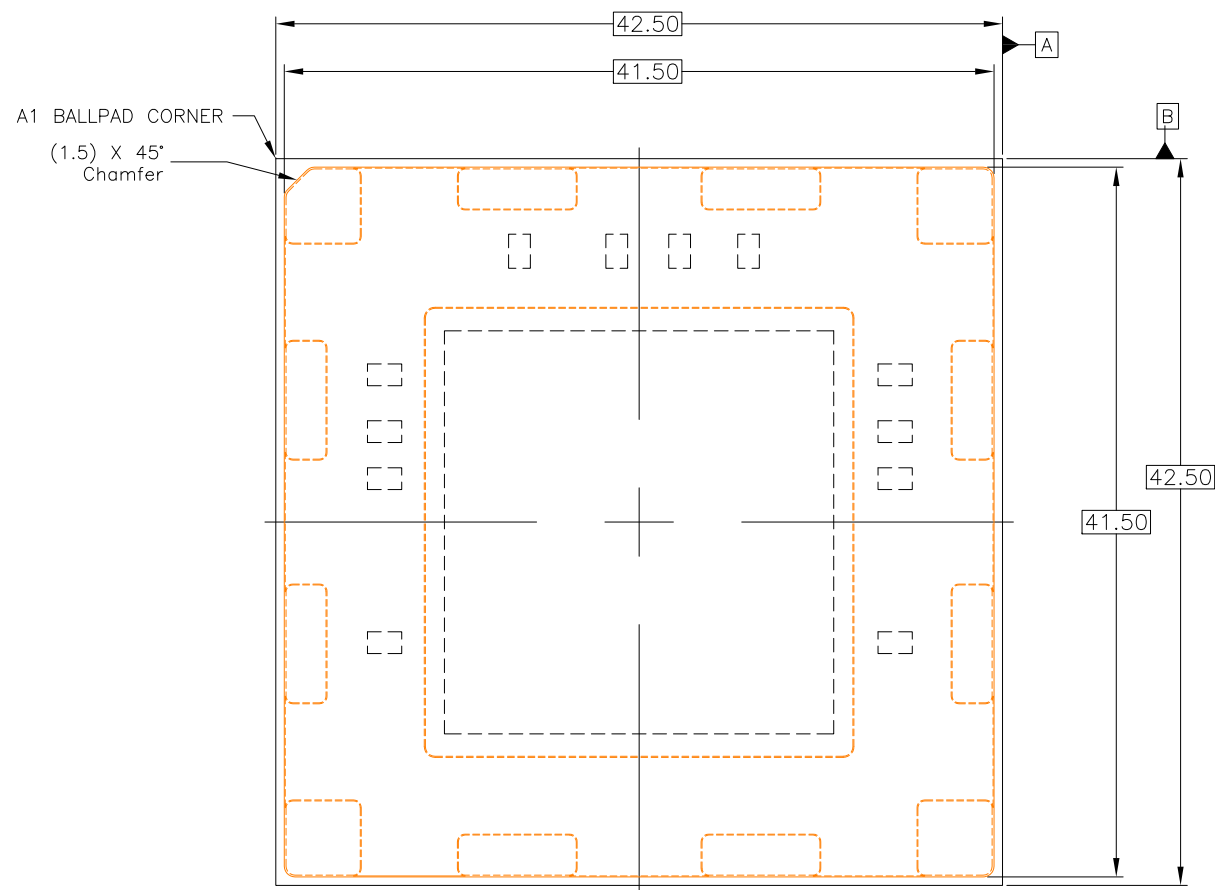


ECN NO.	REV.	DESCRIPTION OF CHANGE	ECN DATE	ORIGINATOR
20190108	0	Preliminary Drawing	12/14/18	Erwin Q.
20200074	1	Revise title from RT4G150M-FCG1657 to RT4G150-FCG1657M, add vendor dwg #.	02/24/20	Erwin Q.



NOTES:

- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

GENERAL TOLERANCE UNLESS OTHERWISE SPECIFIED DECIMAL ANGULAR X.X ±0.1 ±1° X.XX ±0.05 X.XXX ±0.030 INTERPRET DIM AND TOL PER ASME Y14.5M - 2009	PROJECTION: 		MICROSEMI CORPORATION, SOC GROUP 3850 N 1st St San Jose, CA 95134	
	APPROVALS DRAWN: Erwin Q. CHECKED: Raymond K. ENG'R: RELEASED:	DATE 02/24/20 02/24/20	TITLE: RT4G150-FCG1657M, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 SOLDER BALLS, FLIP CHIP, PACKAGE OUTLINE DRAWING	
DIMENSIONS: Millimeters (mm)	VENDOR NAME: Amkor Technology	DWG. NUMBER: 1-14-12021	REV: 1	REV: D
	PART NUMBER: --	VENDOR DWG. NUMBER: 0851877PO	SCALE: NONE	SHEET 1 OF 1